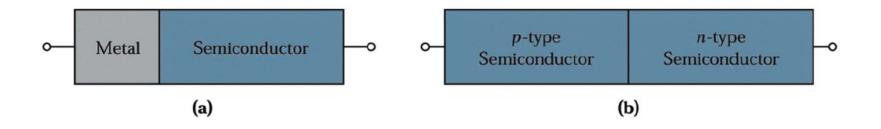
Schottky diode



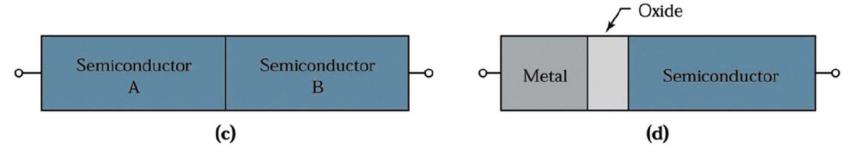


Figure 0.2 © John Wiley & Sons, Inc. All rights reserved.

Basic device building blocks. (a) Metal-semiconductor interface; (b) p-n junction; (c) heterojunction interface; and (d) metal-oxide-semiconductor structure.

Metal-Semiconductor Contacts

There are 2 kinds of metal-semiconductor contacts:

• Rectifying "Schottky diode"

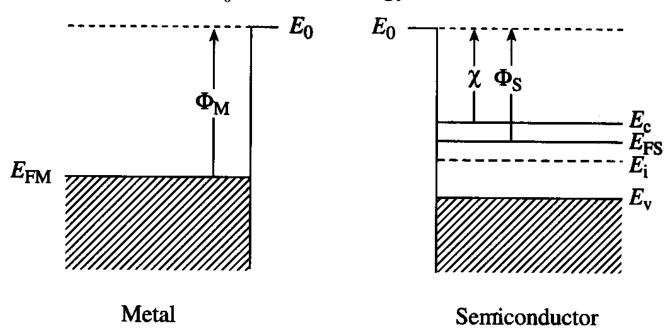
• Non-rectifying "Ohmic contact"

Metal-semiconductor (MS) junctions

- •Many of the properties of pn junctions can be realized by forming an appropriate metal-semiconductor rectifying contact (Schottky contact)
 - Simple to fabricate
 - Switching speed is much higher than that of p-n junction diodes
- •Metal-Semiconductor junctions are also used as ohmiccontact to carry current into and out of the semiconductor device

Work Function

 E_0 : vacuum energy level

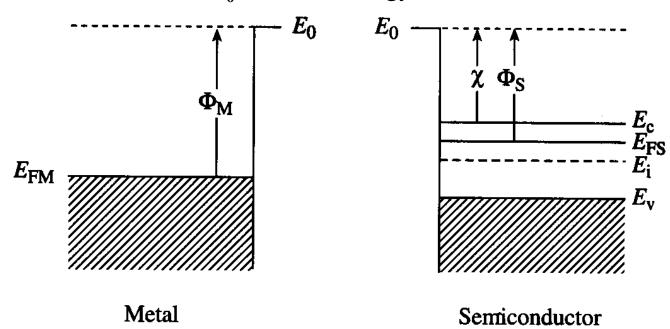


 $\Phi_{\mathbf{M}}$: metal work function

 Φ_{S} : semiconductor work function

Work Function

 E_0 : vacuum energy level



 $\Phi_{\mathbf{M}}$: metal work function

 Φ_{S} : semiconductor work function

Assumptions - Ideal MS contacts

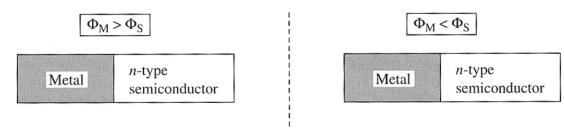
M and S are in intimate contact, on atomic scale No oxides or charges at the interface No intermixing at the interface

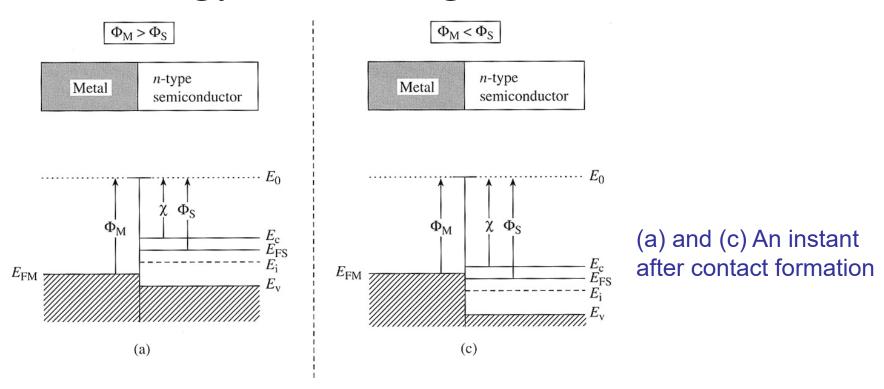
MS contacts

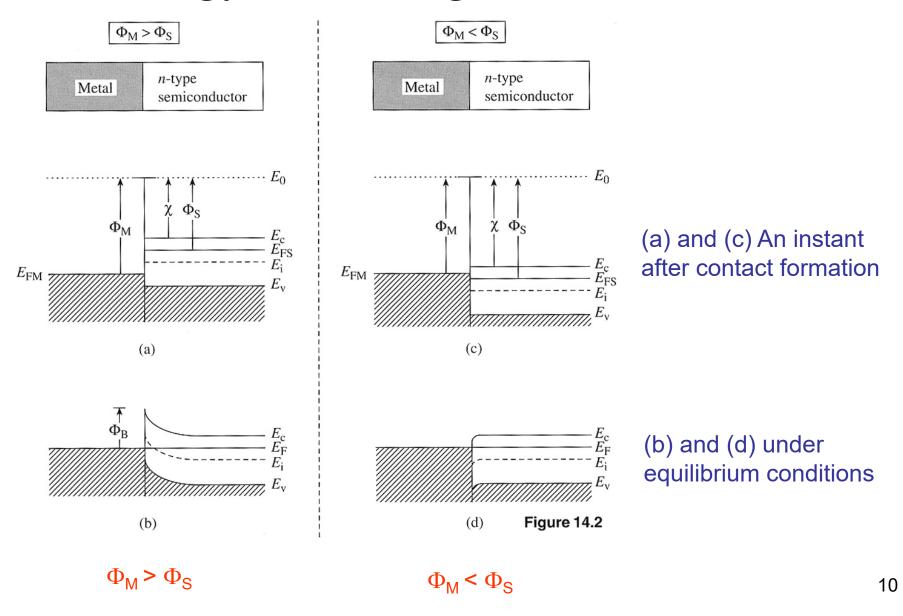
- Vacuum level, E_0 corresponds to energy of free electrons.
- The difference between vacuum level and Fermi-level is called workfunction, Φ of materials.
 - Workfunction, Φ_{M} is an invariant property of metal. It is the minimum energy required to free up electrons from metal. (3.66 eV for Mg, 5.15eV for Ni etc.)
- The semiconductor workfunction, Φ_s , depends on the doping.

$$\Phi_{\rm s} = \chi + (E_{\rm C} - E_{\rm F})$$

• where $\chi = (E_0 - E_C)|_{\text{SURFACE}}$ is a fundamental property of the semiconductor. (Example: $\chi = 4.0 \text{ eV}$, 4.03 eV and 4.07 eV for Ge, Si and GaAs respectively)



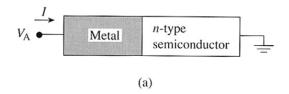




MS (n-type) contact with $\Phi_{\rm M} > \Phi_{\rm S}$

- Soon after the contact formation, electrons will begin to flow from S to M near junction.
- Creates surface depletion layer, and hence a built-in electric field (similar to p⁺-n junction).
- Under equilibrium, net flow of carriers will be zero, and Fermi-level will be constant.
- A barrier Φ_B forms for electron flow from M to S.
- $\Phi_B = \Phi_M \chi$... ideal MS (n-type) contact. Φ_B is called "barrier height".
- Electrons in semiconductor will encounter an energy barrier equal to $\Phi_{\rm M} \Phi_{\rm S}$ while flowing from S to M.

MS (n-type) contact with $\Phi_{\rm M} > \Phi_{\rm S}$



Response to applied bias for n-type semiconductor

Note: An applied positive voltage lowers the band since energy bands are drawn with respect to electron energy.

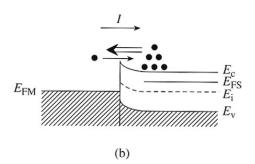
MS (n-type) contact with $\Phi_{\rm M} > \Phi_{\rm S}$

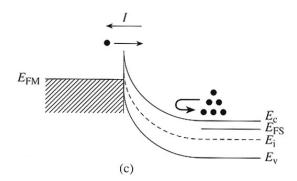
 V_{A} Metal n-type semiconductor

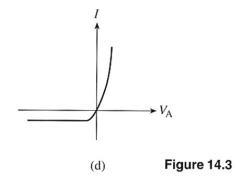
(a)

Response to applied bias for n-type semiconductor

Note: An applied positive voltage lowers the band since energy bands are drawn with respect to electron energy.

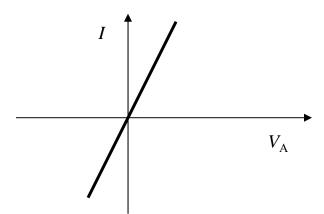


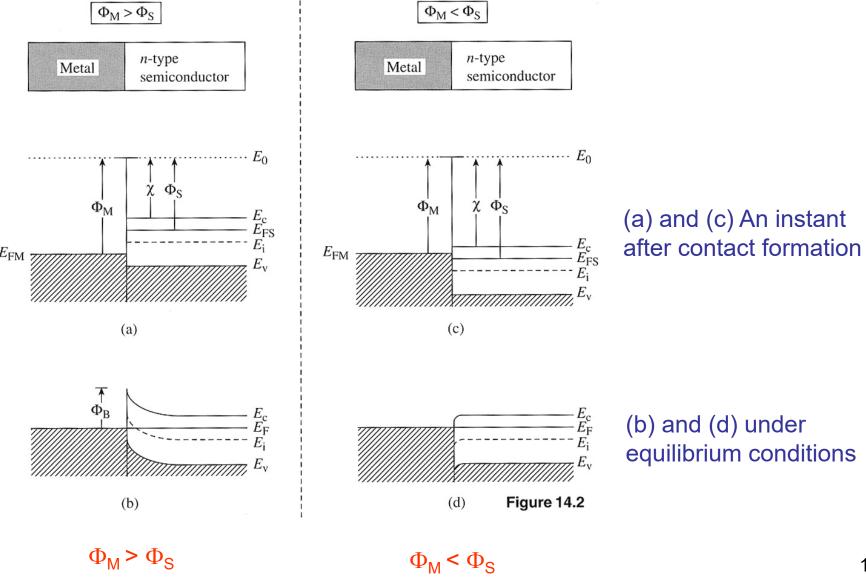




MS (n-type) contact with $\Phi_{\rm M} < \Phi_{\rm S}$

- No barrier for electron flow from S to M.
- So, even a small $V_A > 0$ results in large current.
- As drawn, small barrier exists for electron flow from M to S, but vanishes when $V_A < 0$ is applied to the metal. Large current flows when $V_A < 0$.
- The MS(n-type) contact when $\Phi_{\rm M} < \Phi_{\rm S}$ behaves like an ohmic contact.





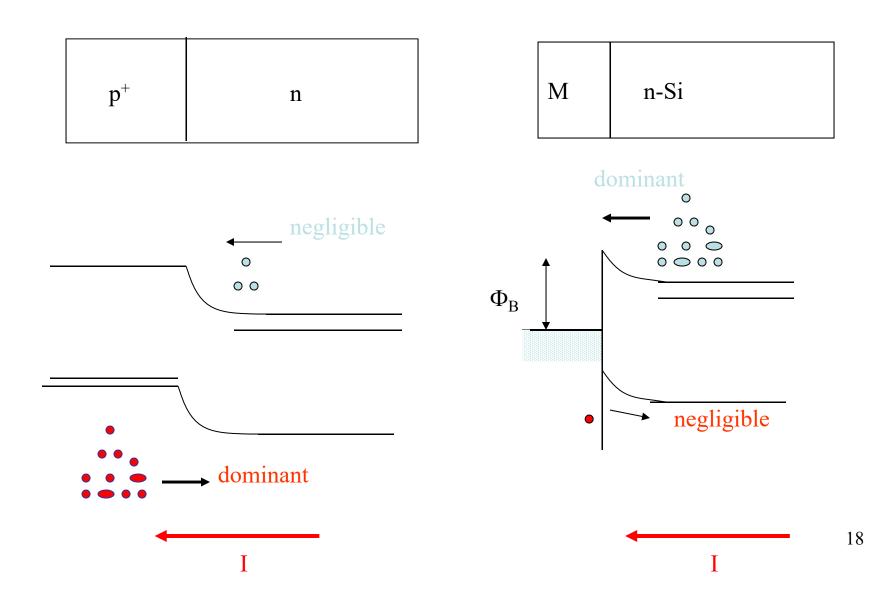
Schottky diode vs pn diode

• MS diode electrostatics and the general shape of the MS diode I-V characteristics are similar to p⁺n diodes, but the details of current flow are different.

Schottky diode vs pn diode

- MS diode electrostatics and the general shape of the MS diode I-V characteristics are similar to p⁺n diodes, but the details of current flow are different.
- Dominant currents in a p⁺n diode
 - arise from recombination in the depletion layer under small forward bias.
 - arise from hole injection from p⁺ side under larger forward bias.
- Dominant currents in a MS Schottky diodes
 - Electron injection from the semiconductor to the metal.

Current components in a p⁺n and MS Schottky diodes

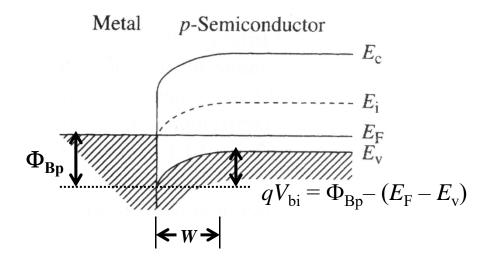


Ideal M-S Contact: $\Phi_{\rm M} < \Phi_{\rm S}$, p-type

Equilibrium band diagram:

Schottky Barrier Height:

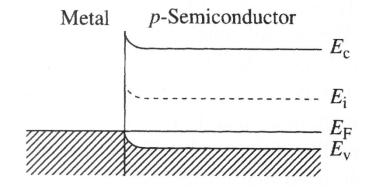
$$\Phi_{\rm Bp} = \chi + E_G - \Phi_{\rm M}$$



p-type semiconductor

Ideal M-S Contact: $\Phi_{\rm M} > \Phi_{\rm S}$, p-type

Equilibrium band diagram:



p-type semiconductor

The Depletion Approximation

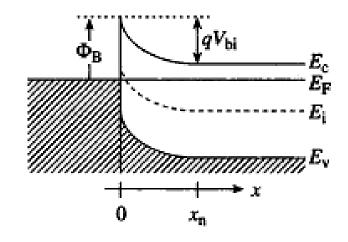
The semiconductor is depleted of mobile carriers to a depth W

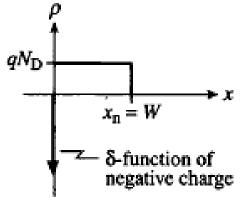
 \Rightarrow In the depleted region (0 \le x \le W):

$$\rho = q (N_D - N_A)$$

Beyond the depleted region (x > W):

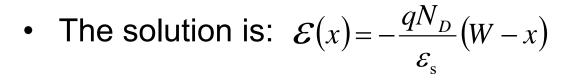
$$\rho$$
 = 0



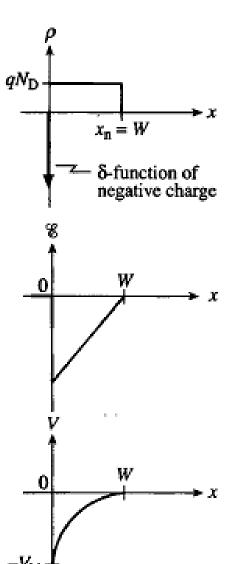


Electrostatics

• Poisson's equation: $\frac{\partial \mathcal{E}}{\partial x} = \frac{\rho}{\varepsilon_s} \cong \frac{qN_D}{\varepsilon_s}$



$$V(x) = -\int \mathcal{E}(x')dx'$$



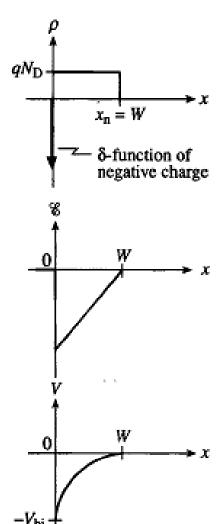
Depletion Width, W

$$V(x) = \frac{-qN_D}{2\varepsilon_s} (W - x)^2$$

At
$$x = 0$$
, $V = -V_{bi}$

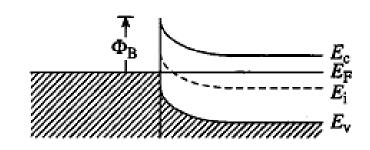
$$\Rightarrow W = \sqrt{\frac{2\varepsilon_s V_{bi}}{qN_D}}$$

• W decreases with increasing N_D

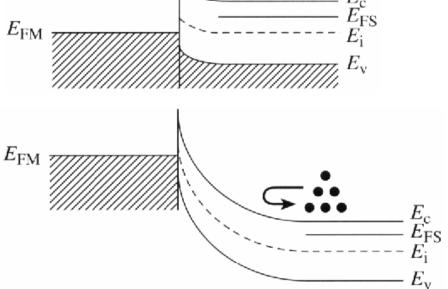


Voltage Drop across the M-S Contact

• Under equilibrium conditions $(V_A = 0)$, the voltage drop across the semiconductor depletion region is the built-in voltage $V_{\rm bi}$.



• If $V_A \neq 0$, the voltage drop across the semiconductor depletion region is V_{bi} - V_A .



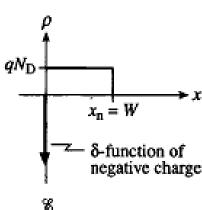
Depletion Width, W, for $V_A \neq 0$

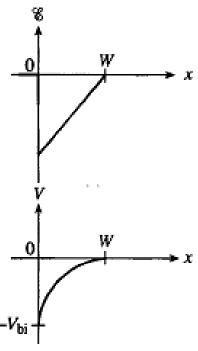
$$V(x) = \frac{-qN_D}{2K_S\varepsilon_0}(W - x)^2$$

At
$$x = 0$$
, $V = -(V_{bi} - V_{A})$

$$\Rightarrow W = \sqrt{\frac{2\varepsilon_s(V_{bi} - V_A)}{qN_D}}$$

- W increases with increasing $-V_A$
- ullet W decreases with increasing $N_{
 m D}$





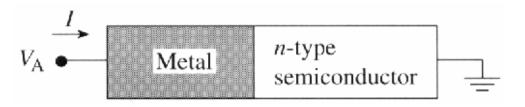
W for p-type Semiconductor

$$V(x) = \frac{qN_A}{2K_S\varepsilon_0}(W - x)^2$$

$$\Rightarrow W = \sqrt{\frac{2\varepsilon_s(V_A + V_{bi})}{qN_A}}$$

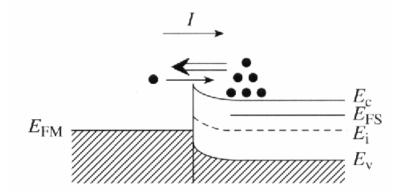
- W increases with increasing $V_{\rm A}$
- ullet W decreases with increasing $N_{
 m A}$

I-V curve

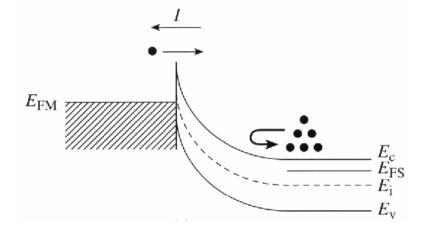


Current Flow

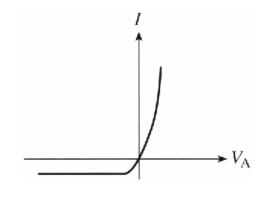
FORWARD BIAS



REVERSE BIAS



- Current is determined by <u>majority-</u> <u>carrier</u> flow across the M-S junction:
 - Under forward bias, majoritycarrier drift from the semiconductor into the metal dominates
 - Under reverse bias, majoritycarrier drift from the metal into the semiconductor dominates

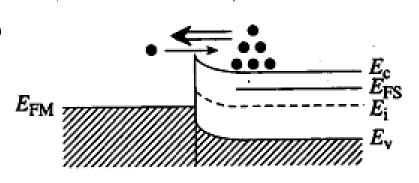


Thermionic Emission Theory

• Electrons can cross the junction into

K.E._x =
$$\frac{1}{2} m v_x^2 \ge q (V_{bi} - V_A)$$

$$|v_x| \ge v_{\min} \equiv \sqrt{\frac{2q}{m_n^*}} (V_{bi} - V_A)$$



• Thus the current for electrons at a given velocity is:

$$I_{s \bullet \to M, v_x} = -qAv_x n(v_x)$$

• So, the total current over the barrier is:

$$I_{s \bullet \to M} = -qA \int_{-\infty}^{-v_{\min}} v_x n(v_x) dv_x$$

Schottky Diode *I* - *V*

For a nondegenerate semiconductor, it can be shown that

$$n(v_x) = \left[\frac{4\pi kTm_n^{*2}}{h^3}\right] e^{(E_F - E_c)/kT} e^{-(m_n^*/2kT)v_x^2}$$

We can then obtain

$$I_{S \bullet \to M} = \frac{4\pi q m_n^* k^2}{h^3} A T^2 e^{-\Phi_B/kT} e^{qV_A/kT}$$

=
$$AJ_S e^{qV_A/kT}$$
, where $J_S = 120 \frac{m_n^*}{m_0} T^2 e^{-\Phi_B/kT}$ A/cm²

In the reverse direction, the electrons always see the same barrier

 $\Phi_{\rm B}$, so

$$I_{M \bullet \to S} = -I_{S \bullet \to M} (V_A = 0)$$

Therefore
$$I = I_S(e^{qV_A/kT} - 1)$$
 where $I_S = AJ_S$

Practical Ohmic Contact

• In practice, most M-S contacts are rectifying

- To achieve a contact which conducts easily in both directions, we dope the semiconductor very heavily
 - \rightarrow W is so narrow that carriers can "tunnel" directly through the barrier

Tunneling Current Density

Equilibrium Band Diagram Band Diagram for $V_A \neq 0$

$$W \cong \sqrt{\frac{2\varepsilon_{s}\Phi_{Bn}}{qN_{D}}} \quad \textbf{\textit{E}}_{FM} \xrightarrow{q} \textbf{\textit{V}}_{bi} \cong \Phi_{Bn} \textbf{\textit{E}}_{c}, \textbf{\textit{E}}_{FS} \quad \textbf{\textit{E}}_{FM} \xrightarrow{q} \textbf{\textit{V}}_{bi} = \textbf{\textit{V}}_{A}) \quad \textbf{\textit{E}}_{c}, \textbf{\textit{E}}_{FS} \quad \textbf{\textit{E}}_{FS} \quad \textbf{\textit{E}}_{FS} = \textbf{\textit{E}}_{V} = \textbf{\textit{E}}_{V}$$

tunneling probability $P = e^{-H(\Phi_{Bn}-V_A)/\sqrt{N_D}}$

where
$$H = 4\pi \sqrt{\varepsilon_s m_n^*} / h = 5.4 \times 10^9 \sqrt{m_n^* / m_o} \text{ cm}^{-3/2} \text{V}^{-1}$$

$$J_{S \to M} \approx qPN_D v_{thx} = qN_D \sqrt{kT/2\pi m_n^*} e^{-H(\Phi_{Bn}-V_A)/\sqrt{N_D}}$$

~The end~